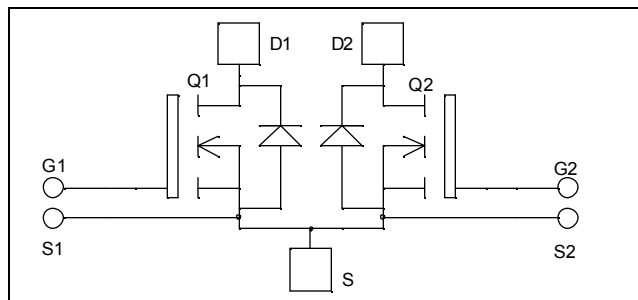


Dual common source MOSFET Power Module

$V_{DSS} = 1200V$

$R_{DSon} = 150m\Omega$ typ @ $T_j = 25^\circ C$

$I_D = 60A$ @ $T_c = 25^\circ C$



Application

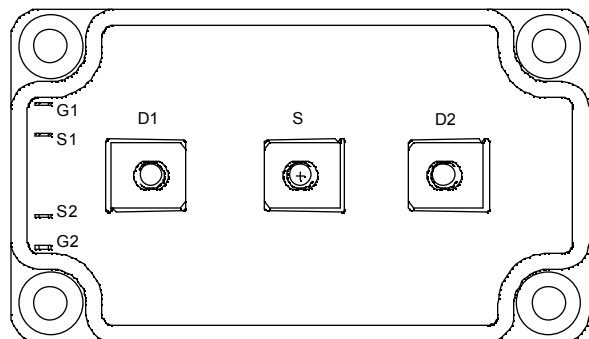
- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	1200	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$ 60	A
		$T_c = 80^\circ C$ 45	
I_{DM}	Pulsed Drain current	240	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	175	$m\Omega$
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$ 1250	W
I_{AR}	Avalanche current (repetitive and non repetitive)	22	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	

 **CAUTION:**

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 1200V$ $T_j = 25^\circ\text{C}$			500	μA
		$V_{GS} = 0V, V_{DS} = 1000V$ $T_j = 125^\circ\text{C}$			3000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 30A$		150	175	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 250	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{MHz}$		20.6		nF
C_{oss}	Output Capacitance			3.08		
C_{rss}	Reverse Transfer Capacitance			0.52		
Q_g	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 600V$ $I_D = 60A$		748		nC
Q_{gs}	Gate – Source Charge			96		
Q_{gd}	Gate – Drain Charge			480		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 800V$ $I_D = 60A$ $R_G = 1.2\Omega$		20		ns
T_r	Rise Time			15		
$T_{d(off)}$	Turn-off Delay Time			160		
T_f	Fall Time			45		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 800V$ $I_D = 60A, R_G = 1.2\Omega$		3.96		mJ
E_{off}	Turn-off Switching Energy			2.74		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 800V$ $I_D = 60A, R_G = 1.2\Omega$		6.26		mJ
E_{off}	Turn-off Switching Energy			3.43		

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)	$T_c = 25^\circ\text{C}$			60	A
		$T_c = 80^\circ\text{C}$			45	
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -60A$			1.3	V
dv/dt	Peak Diode Recovery ❶				10	V/ns
t_{rr}	Reverse Recovery Time	$I_S = -60A, V_R = 600V$ $di_S/dt = 400A/\mu\text{s}$		1291		ns
Q_{rr}	Reverse Recovery Charge			116		μC

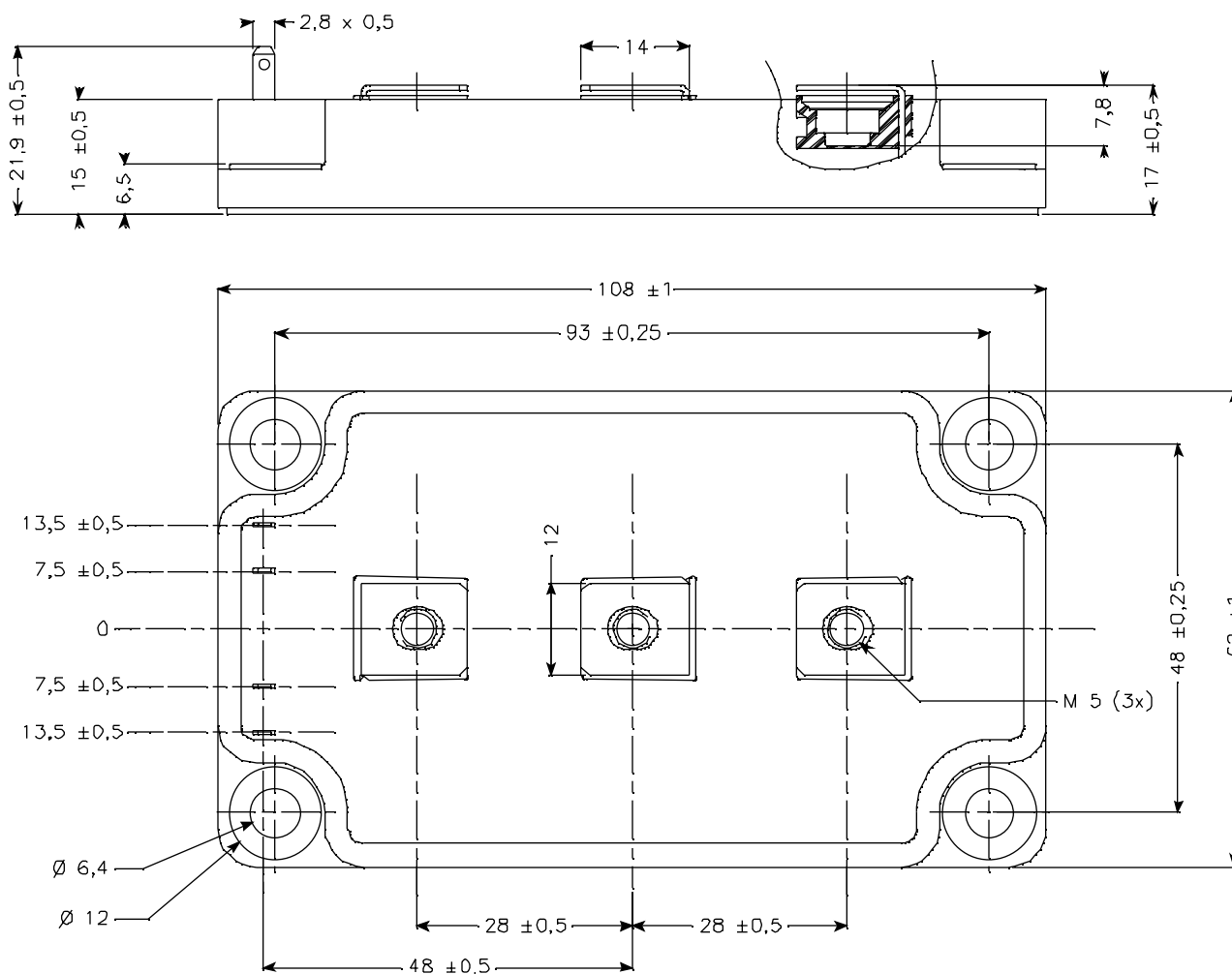
❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$I_S \leq -60A$ $di/dt \leq 700A/\mu\text{s}$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ\text{C}$

Thermal and package characteristics

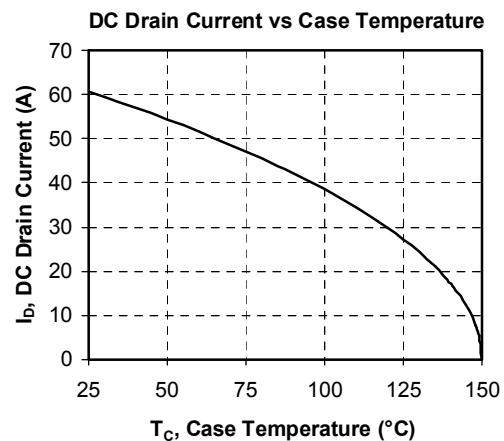
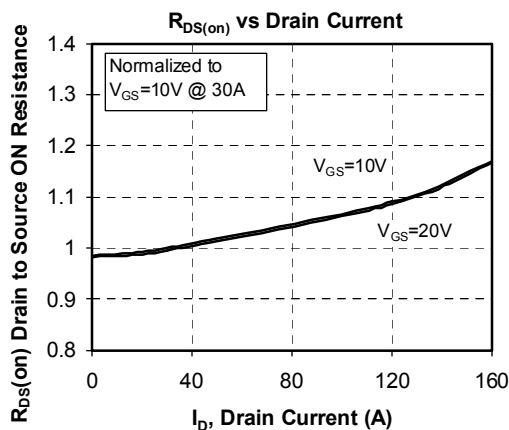
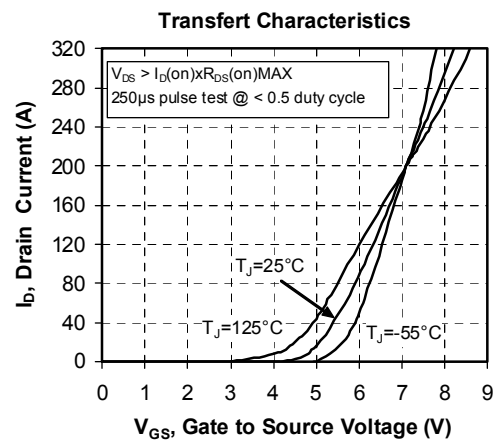
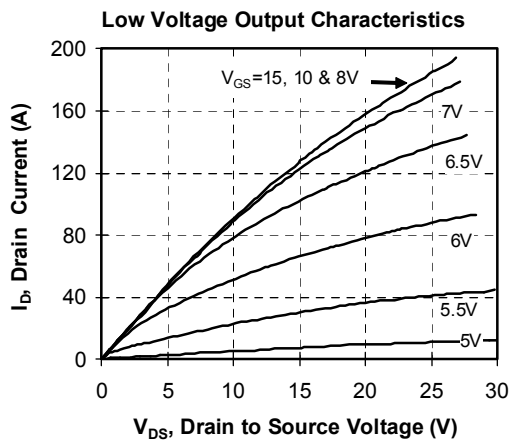
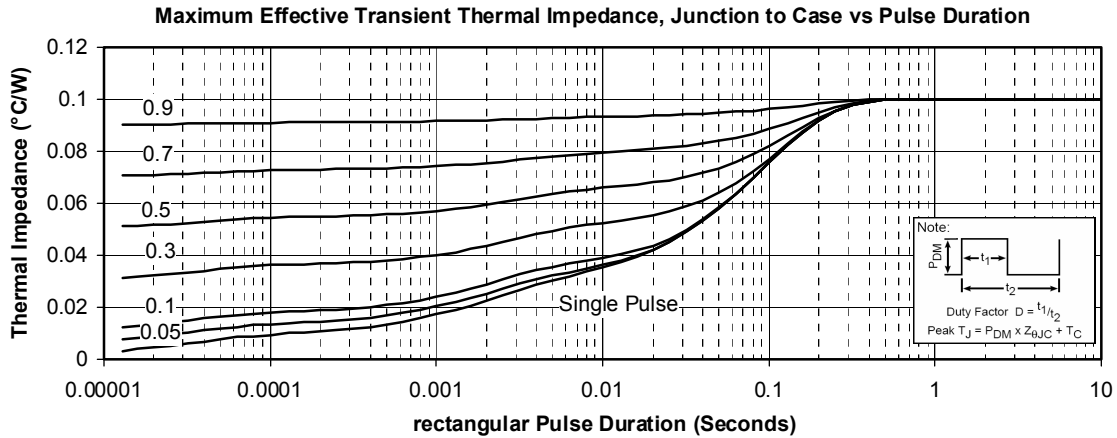
Symbol	Characteristic			Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance					0.1	°C/W
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz			2500			V
T _J	Operating junction temperature range			-40		150	°C
T _{STG}	Storage Temperature Range			-40		125	
T _C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					280	g

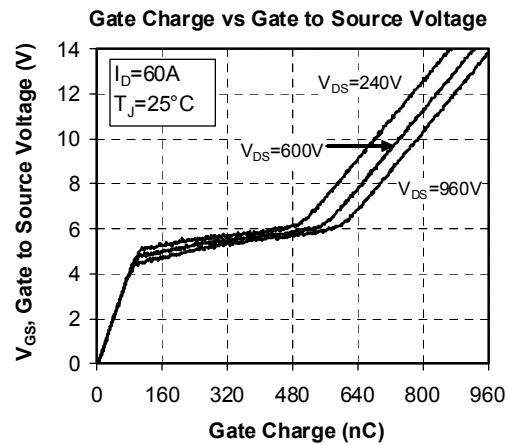
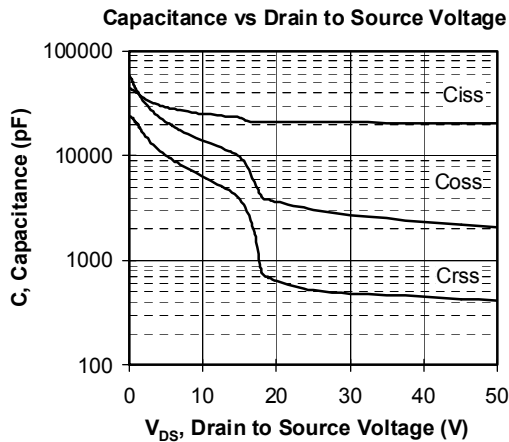
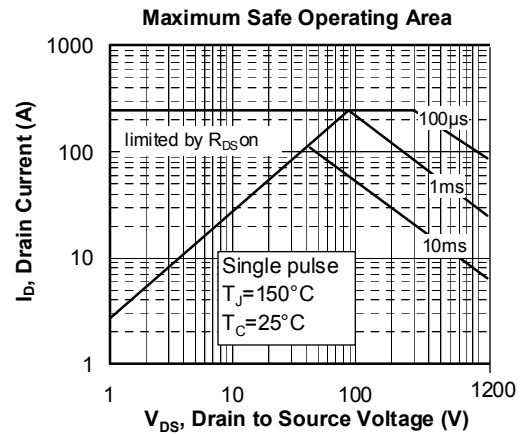
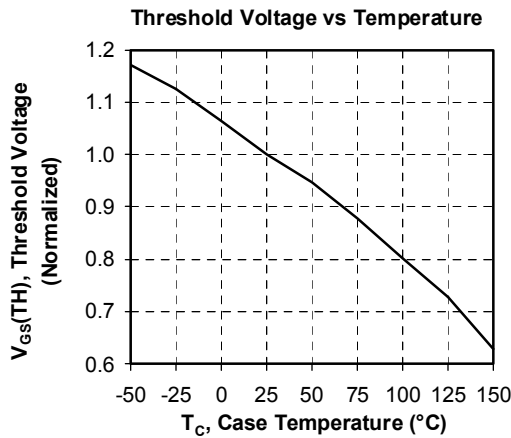
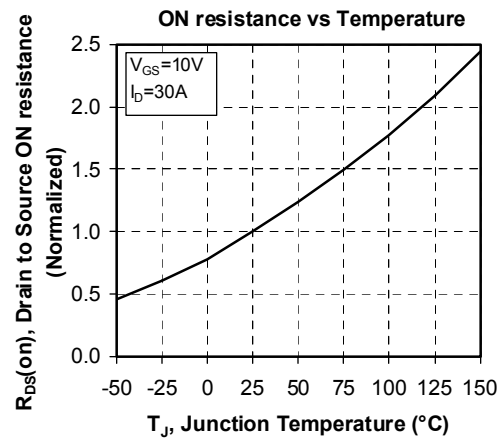
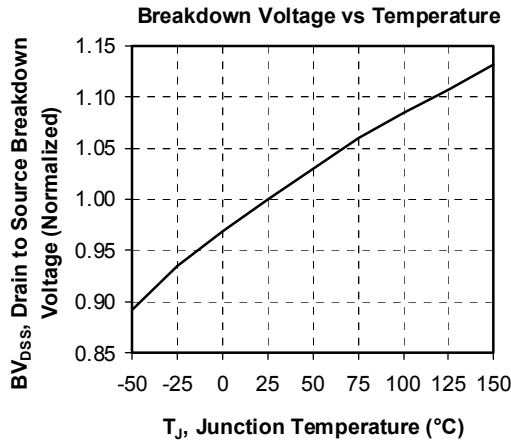
SP6 Package outline (dimensions in mm)

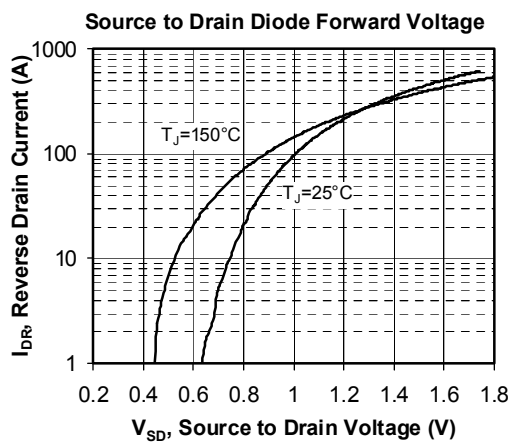
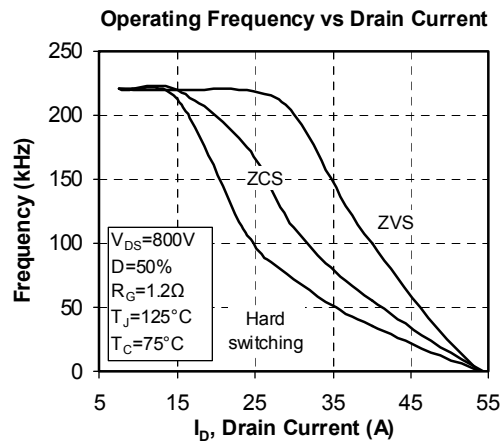
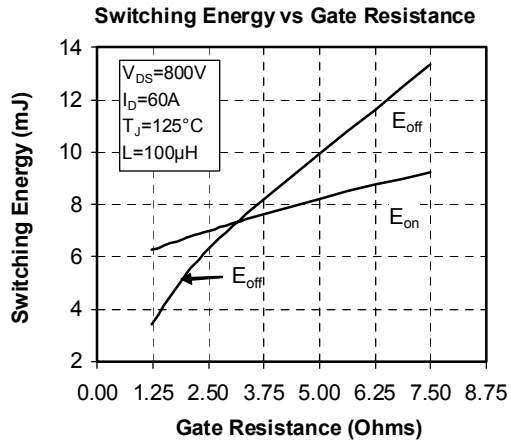
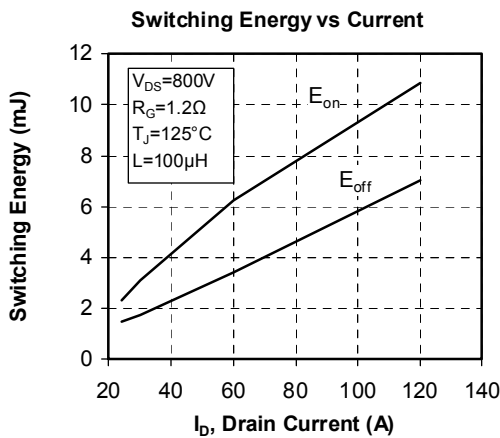
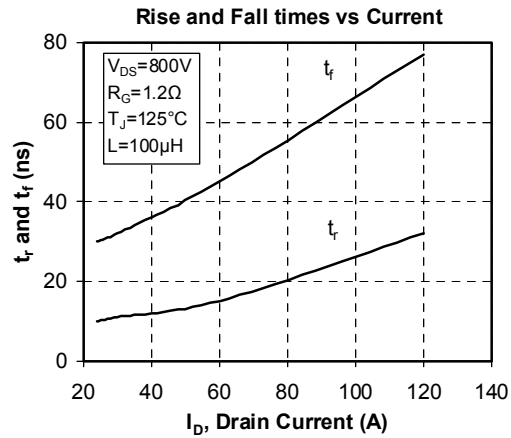
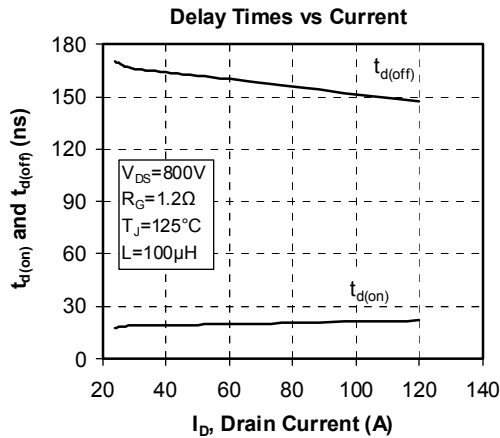


See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve







Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.

